JEDEC
STANDARD

GRAPHICS DOUBLE DATA RATE (GDDR6) SGRAM STANDARD

JESD250B
(Revision of JESD250A, July 2017)

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JEDEC SOLID STATE TECHNOLOGY ASSOCIATION

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GRAPHICS DOUBLE DATA RATE 6 (GDDR6) SGRAM

(From JEDEC Board ballot JCB-18-48, formulated under the cognizance of the JC-42.3C Letter Committee on DRAM Parametrics.)

1 SCOPE

This document defines the Graphics Double Data Rate 6 (GDDR6) Synchronous Graphics Random Access Memory (SGRAM) specification, including features, functionality, package, and pin assignments.

The purpose of this Specification is to define the minimum set of requirements for 8 Gb through 16 Gb x16 dual channel GDDR6 SGRAM devices. System designs based on the required aspects of this standard will be supported by all GDDR6 SGRAM vendors providing compatible devices. Some aspects of the GDDR6 standard such as AC timings and capacitance values were not standardized. Some features are optional and therefore may vary among vendors. In all cases, vendor data sheets should be consulted for specifics. This document was created based on some aspects of the GDDR5 Standard (JESD212).